

1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任 何异议请及时告之,我们将妥善解决。

本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。

3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。

4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

## **Read Statement**

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.

2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.

3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.

4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets".



### 20W Hi-Fi AUDIO POWER AMPLIFIER

#### DESCRIPTION

The TDA2040 is a monolithic integrated circuit in Pentawatt ® package, intended for use as an audio class AB amplifier. Typically it provides 22W output power (d = 0.5%) at V<sub>s</sub> = 32V/4 $\Omega$ . The TDA2040 provides high output current and has very low harmonic and cross-over distortion. Further the device incorporates a patented short circuit protection system comprising an arrangement for automatically limiting the dissipated power so as to keep the working point of the output transistors within their safe operating area. A thermal shut-down system is also included.



#### **TEST CIRCUIT**



#### SCHEMATIC DIAGRAM



#### **PIN CONNECTION**



#### THERMAL DATA

Symbol	Parameter	Value	Unit
R <sub>th j-case</sub>	Thermal Resistance Junction-case Max.	3	°C/W

57

#### 2/13

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
Vs	Supply Voltage	± 20	V
Vi	Input Voltage	Vs	
Vi	Differential Input Voltage	± 15	V
lo	Output Peak Current (internally limited)	4	Α
Ptot	Power Dissipation at T <sub>case</sub> = 75 °C	25	W
T <sub>stg</sub> , T <sub>j</sub>	Storage and Junction Temperature	– 40 to + 150	°C

#### ELECTRICALCHARACTERISTICS

57

(refer to the test circuit,  $V_S$  =  $\pm$  16V,  $T_{amb}$  = 25  $^oC$  unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Vs	Supply Voltage		± 2.5		± 20	V
l <sub>d</sub>	Quiescent Drain Current	$\begin{array}{l} V_s=\pm  4.5 V \\ V_s=\pm  20 V \end{array}$		45	30 100	mA mA
lb	Input Bias Current	$V_s = \pm 20V$		0.3	1	μA
Vos	Input Offset Voltage	$V_s = \pm 20V$		± 2	± 20	mV
los	Input Offset Current				$\pm200$	nA
Po	Output Power	$\label{eq:constraint} \begin{array}{l} d=0.5\%,T_{case}=60^\circ C\\ f=1kHz & R_L=4\Omega\\ R_L=8\Omega\\ f=15kHz & R_L=4\Omega \end{array}$	20 15	22 12 18		W
BW	Power Bandwidth	$P_o = 1W, R_L = 4\Omega$		100		kHz
Gv	Open Loop Voltage Gain	f = 1kHz		80		dB
Gv	Closed Loop Voltage Gain	f = 1kHz	29.5	30	30.5	dB
d	Total Harmonic Distortion	$\begin{array}{l} P_{o} = 0.1 \text{ to } 10W, R_{L} = 4\Omega \\ f = 40 \text{ to } 15000Hz \\ f = 1kHz \end{array}$		0.08 0.03		%
e <sub>N</sub>	Input Noise Voltage	B = Curve A B = 22Hz to 22kHz		2 3	10	μV μV
i <sub>N</sub>	Input Noise Current	B = Curve A B = 22Hz to 22kHz		50 80	200	pА
Ri	Input Resistance (pin 1)		0.5	5		MΩ
SVR	Supply Voltage Rejection	$ \begin{array}{l} R_L = 4\Omega,  R_g = 22k\Omega,  G_v = 30dB \\ f = 100Hz,  V_{ripple} = 0.5V_{RMS} \end{array} $	40	50		dB
η	Efficiency			66 63		%
Tj	Thermal Shut-down Junction Temperature			145		°C

G- 6032  $R_{L} = 4\Omega$ POUT Gy=30dB d=0.5% f=1KHz (W) 26 22 18 RL = 8.0. 14 10 6 2 5 7 9 11 13 15  $\pm v_s(v)$ 

Figure 1: Output Power versus Supply Voltage

Figure 3: Output Power versus Supply Voltage



Figure 5 : Supply Voltage Rejection versus Frequency



Figure 2: Output Power versus Supply Voltage



Figure 4 : Distortion versus Frequency



Figure 6 : Supply Voltage Rejection versus Voltage Gain



67/

Figure 7 : Quiescent Drain Current versus Supply Voltage



Figure 9 : Power Dissipation versus Output Power



Figure 8 : Open Loop Gain versus Frequency



57





Figure 11 : P.C. Board and Components Layout for the Circuit of Figure 10 (1:1 scale)





Figure 12 : Amplifier with Split Power Supply (see Note)





![](_page_8_Figure_1.jpeg)

Figure 14 : 30W Bridge Amplifier with Split Power Supply

Figure 15 : P.C. Board and Components Layout for the Circuit of Figure 14 (1:1 scale)

![](_page_8_Figure_4.jpeg)

![](_page_9_Figure_1.jpeg)

Figure 16 : Two Way Hi-Fi System with Active Crossover

![](_page_9_Figure_3.jpeg)

![](_page_9_Figure_4.jpeg)

Figure 18 : Frequency Response

![](_page_10_Figure_2.jpeg)

## MULTIWAY SPEAKER SYSTEMS AND ACTIVE BOXES

Multiway loudspeaker systems provide the best possible acoustic performance since each loudspeaker is specially designed and optimized to handle a limited range of frequencies. Commonly, these loudspeaker systems divide the audio spectrum into two, three or four bands.

To maintain a flat frequency response over the Hi-Fi audio range the bands covered by each loudspeaker must overlap slightly. Imbalance between the loudspeakers produces unacceptable results therefore it is important to ensure that each unit generates the correct amount of acoustic energy for its segment of the audio spectrum. In this respect it is also important to know the energy distribution of the music spectrum determine the cutoff frequencies of the crossover filters (see Figure 19). As an example, a 100W three-way system with crossover frequencies of 400Hz and 3kHz would require 50W for the woofer, 35W for the midrange unit and 15W for the tweeter.

Both active and passive filters can be used for crossovers but today active filters cost significantly less than a good passive filter using air-cored inductors and non-electrolytic capacitors. In addition, active filters do not suffer from the typical defects of passive filters :

- power loss
- increased impedance seen by the loudspeaker (lower damping)
- difficulty of precise design due to variable loudspeaker impedance

Obviously, active crossovers can only be used if a

![](_page_10_Figure_11.jpeg)

![](_page_10_Figure_12.jpeg)

power amplifier is provided for each drive unit. This makes it particularly interesting and economically sound to use monolithic power amplifiers. In some applications, complex filters are not really necessary and simple RC low-pass and high-pass networks (6dB/octave) can be recommended.

The results obtained are excellent because this is the best type of audio filter and the only one free from phase and transient distortion.

The rather poor out of band attenuation of single RC filters means that the loudspeaker must operate linearly well beyond the crossover frequency to avoid distortion.

A more effective solution, named "Active Power Filter" by SGS is shown in Figure 20.

Figure 20 : Active Power Filter

![](_page_10_Figure_18.jpeg)

The proposed circuit can realize combined power amplifiers and 12dB/octave or 18dB/octave high-pass or low-pass filters.

In practice, at the input pins of the amplifier two equal and in-phase voltages are available, as required for the active filter operation.

![](_page_10_Picture_22.jpeg)

The impedance at the pin (-) is of the order of  $100\Omega$ , while that of the pin (+) is very high, which is also what was wanted.

C1 = C2 = C3	R1	R2	R3
22 nF	8.2 kΩ	5.6 kΩ	33 kΩ

The component values calculated for  $f_{c}$  = 900Hz using a Bessel 3rd order Sallen and Key structure are :

In the block diagram of Figure 21 is represented an active loudspeaker system completely realized using power integrated circuit, rather than the traditional discrete transistors on hybrids, very high quality is obtained by driving the audio spectrum into three bands using active crossovers (TDA2320A) and a separate amplifier and loudspeakers for each band.

A modern subwoofer/midrange/tweeter solution is used.

#### PRATICAL CONSIDERATION

#### **Printed Circuit Board**

The layout shown in Figure 11 should be adopted by the designers. If different layouts are used, the ground points of input 1 and input 2 must be well decoupled from the gorund return of the output in which a high current flows.

#### **Assembly Suggestion**

No electrical isolation is needed between the package and the heatsink with single supply voltage configuration.

#### **Application Suggestions**

The recommended values of the components are those shown on application circuit of Fig. 10. Different values can be used. The following table can help the designer.

![](_page_11_Figure_13.jpeg)

Comp.	Recom. Value	Purpose	Larger than Recommended Value	Smaller than Recommended Value
R1	22kΩ	Non inverting input biasing	Increase of input impedance	Decrease of input impedance
R2	680Ω	Closed loop gain setting	Decrease of gain (*)	Increase of gain
R3	22kΩ	Closed loop gain setting	Increase of gain	Decrease of gain (*)
R4	4.7Ω	Frequency stability	Danger of oscillation at high frequencies with inductive loads	
C1	1μF	Input DC decoupling		Increase of low frequencies cut-off
C2	22µF	Inverting DC decoupling		Increase of low frequencies cut-off
C3, C4	0.1µF	Supply voltage bypass		Danger of oscillation
C5, C6	220µF	Supply voltage bypass		Danger of oscillation
C7	0.1µF	Frequency stability		Danger of oscillation

(\*) The value of closed loop gain must be higher than 24dB  $\,$ 

![](_page_11_Picture_16.jpeg)

DIM	mm			inch		
DIN.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			4.8			0.189
С			1.37			0.054
D	2.4		2.8	0.094		0.110
D1	1.2		1.35	0.047		0.053
Е	0.35		0.55	0.014		0.022
E1	0.76		1.19	0.030		0.047
F	0.8		1.05	0.031		0.041
F1	1.0		1.4	0.039		0.055
G	3.2	3.4	3.6	0.126	0.134	0.142
G1	6.6	6.8	7.0	0.260	0.268	0.276
H2			10.4			0.409
H3	10.05		10.4	0.396		0.409
L	17.55	17.85	18.15	0.691	0.703	0.715
L1	15.55	15.75	15.95	0.612	0.620	0.628
L2	21.2	21.4	21.6	0.831	0.843	0.850
L3	22.3	22.5	22.7	0.878	0.886	0.894
L4			1.29			0.051
L5	2.6		3.0	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6.0		6.6	0.236		0.260
L9	2.1		2.7	0.008		0.106
L10	4.3		4.8	0.17		0.189
М	4.23	4.5	4.75	0.167	0.178	0.187
M1	3.75	4.0	4.25	0.148	0.157	0.167
V4	40° (typ.)					
V5	90° (typ.)					
Dia	3.65		3.85	0.144		0.152

# **OUTLINE AND MECHANICAL DATA** Weight: 2.00gr

Pentawatt V

![](_page_12_Figure_4.jpeg)

12/13

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners

© 2003 STMicroelectronics - All rights reserved

STMicroelectronics GROUP OF COMPANIES

Australia – Belgium - Brazil - Canada - China – Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States www.st.com

![](_page_13_Picture_6.jpeg)